

## (19) United States

# (12) Patent Application Publication (10) Pub. No.: US 2024/0213350 A1

**Torres Alonso** 

Jun. 27, 2024 (43) **Pub. Date:** 

### (54) GRAPHENE DEVICE AND METHOD OF METALLIZING A GRAPHENE DEVICE

(71) Applicant: Graphenea Semiconductor S.L.U.,

Donostia - San Sebastián (Guipúzcoa)

(ES)

(72) Inventor: Elías Torres Alonso, Donostia - San

Sebastián (Guipúzcoa) (ES)

Appl. No.: 18/525,091 (21)

Filed: Nov. 30, 2023 (22)

(30)Foreign Application Priority Data

Dec. 23, 2022 (EP) ...... 22383280.9

#### **Publication Classification**

(51) Int. Cl. H01L 29/66 (2006.01)H01L 29/16 (2006.01)

(52) U.S. Cl. CPC .... H01L 29/66045 (2013.01); H01L 29/1606 (2013.01)

#### (57)**ABSTRACT**

A method of metallizing a solid-state device including a substrate and at least one graphene channel on the substrate includes applying a first metal deposition stage for depositing at least one first metallic structure, the metallic structure partially occupying the graphene layer and the substrate, wherein a metal deposition technique which does not use plasma is used to deposit the metallic structure; applying a second metal deposition stage for depositing at least one second metallic structure on a region of the first metallic structure not deposited on the graphene channel. A solidstate device includes at least two metallic structures, one partially occupying the graphene layer and the substrate and one partially deposited on a region of the at least one first metallic structure which is not deposited on the graphene channel. A method of packaging in a socket a die having at least one graphene-based solid-state device is related.

